



Schedule of Scope to Certificate of Conformity

Approved Component - Capability

IECQ Certificate No.: IECQ-C BSI 14.0052

CB Certificate No.: 029/ICA

Schedule Number: IECQ-C BSI 14.0052-S

Rev No.: 5

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Page 1 of 1

Test Reports:

7293042	4 March 2009
38590	25 March 2009
8011	27 Sept 2021

Board Types Multilayer boards with blind and/or buried vias (Type 4) IPC 6012E Class 3
Multilayer boards without blind or buried vias (Type 3)
Double-sided boards (Type 2)
Single-sided boards (Type 1)

Base Materials: Epoxide woven glass IPC 4101/26
(21, 24, 98, 99, 101, 126)

Board Size: 405 mm x 280 mm (Type 3 & 4)
500 mm x 360 mm (Type 1 & 2)

Conductors: Minimum width: 0.1 mm ± 0.05mm 12 µm foil
Minimum spacing: 0.1 mm ± 0.05mm 18 µm foil

Number of Layers: 16 (Class 2), 12 (Class 3) Maximum

Plated-through hole Diameter: 0.5 mm minimum drilled

Aspect Ratio: 6.4 : 1 (Class 2), 4.6 : 1 (Class 3) Maximum

Finishes: 63:37 Sn/Pb Hot Air Solder Level
Electroless Nickel / Immersion Gold
Electrolytic Nickel and Gold
Organic Solderability Preservative
Immersion Silver
Photoimageable solder resist
IR Cured Notation Ink

Additional: Bonded Heatplanes: Anodized Aluminium
Nickel Plated Copper

Note: It may not be possible to achieve the limits of the capability in combination. Such combinations are determined by the agreed customer detail specification for the PCB ordered.

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